



Product Change Notification - LIAL-25IXJB026

Date:

28 Mar 2018

Product Category:

Ethernet Switches

Affected CPNs:**Notification subject:**

CCB 3287, 3287.001 Initial Notice: Qualification of ASE as a new assembly site for selected products of the 0.18um wafer technology available in 64L (10x10x1.4mm) and 48L LQFP (7x7x1.4mm) packages.

Notification text:**PCN Status:**

Initial notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as a new assembly site for selected products of the 0.18um wafer technology available in 64L (10x10x1.4mm) and 48L LQFP (7x7x1.4 mm) packages.

Pre Change:

Assembled at TICIP assembly site using EN4900 die attach material and CEL-9200 mold compound material.

Post Change:

Assembled at ASE assembly site using CRM-1076WA die attach material and EME-G631H mold compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Taiwan IC Packing Corp. (TICIP)	ASE Inc. (ASE)
Wire material	Au	Au
Die attach material	EN4900	CRM-1076WA
Molding compound material	CEL-9200	EME-G631H
Lead frame material	C7025	C7025

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying ASE as new assembly site

Change Implementation Status:

In Progress



Estimated Qualification Completion Date:

August 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	March 2018					-->	August 2018				
	09	10	11	12	13		31	32	33	34	35
Initial PCN Issue Date	X										
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

March 1, 2018: Issued initial notification.

March 21, 2018: Revised this initial notification to be issued to all affected customers.

March 28, 2018: Re-issued initial notification to update the subject with reference to CCB 3287.001.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_LIAL-25IXJB026_QUAL_PLAN.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

KSZ8863FLL
KSZ8863FLLI
KSZ8863FLLI-TR
KSZ8863FLL-TR
KSZ8863MLL
KSZ8863MLLI
KSZ8863MLLI-TR
KSZ8863RLL
KSZ8863RLLI
KSZ8863RLLI-TR
SPNZ801077
SPNZ801080
SPNZ801081
KSZ8873FLL
KSZ8873FLLI
KSZ8873MLL
KSZ8873MLLI
KSZ8873MLLJ
KSZ8873MML
KSZ8873MMLI
KSZ8873RLL
KSZ8873RLLI
KSZ8873RLLI-TR